

TM

MMSD914

Features

- Compact surface mount with same footprint as Minimef
- 400 milliwatt Power Dissipation package
- High Breakdown Voltage, Fast Switching Speed
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0 and MSL Rating 1
- Marking:5D
- Lead Free Finish/RoHS Compliant("P" Suffix designates RoHS Compliant. See ordering information)

400mW Fast Switching Diodes

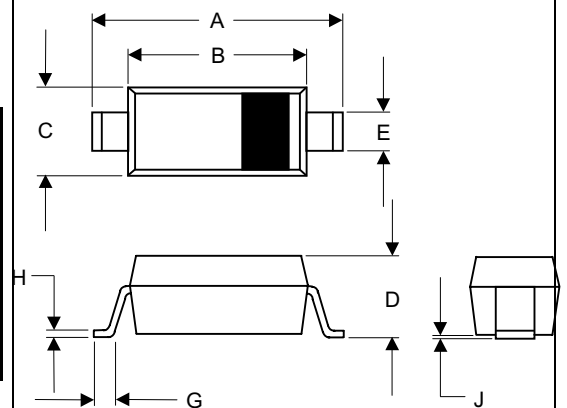
Maximum Ratings

Symbol	Rating	Rating	Unit
W_{IV}	Working Inverse Voltage	75	V
I_{FM}	Forward Continuous Current	600	mA
I_O	Average Rectified Output Current	200	mA
I_{FSM}	Peak Forward Surge Current @1.0 μ s @1.0s	2.0 1.0	A
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	312	$^{\circ}C/W$
P_D	Power dissipation	400	mW
T_J	Junction Temperature	-55 to +150	$^{\circ}C$
T_{STG}	Storage Temperature	-55 to +150	$^{\circ}C$

Electrical Characteristics @ 25°C Unless Otherwise Specified

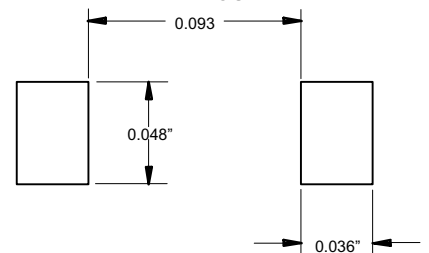
Symbol	Parameter	Min	Max	Test Conditions
$V_{(BR)}$	Reverse Breakdown Voltage	100V 75V		$I_R=100 \mu A$ $I_R=5 \mu A$
I_R	Reverse Voltage Leakage Current		5 μA 25nA	$V_R=75V$ $V_R=20V$
V_F	Forward Voltage		1.0V	$I_F=10mA$
C_T	Total Capacitance		4pF	$V_R=0V, f=1MHz$
t_{rr}	Reverse Recovery Time		4ns	$V_R=6V, I_{rr}=0.1x I_R$ $I_F=I_R=10mA$

SOD123



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.140	.152	3.55	3.85	
B	.100	.112	2.55	2.85	
C	.055	.071	1.40	1.80	
D	-----	.053	-----	1.35	
E	.012	.031	0.30	.78	
G	.006	-----	0.15	-----	
H	-----	.01	-----	.25	
J	-----	.006	-----	.15	

SUGGESTED SOLDER PAD LAYOUT



Ordering Information

Device	Packing
(Part Number)-TP	Tape&Reel;3Kpcs/Reel